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ABSTRACT

The invention concerns a process of selective transfer of labels from an initial support to a final support, each label including at least one element constituent of a microelectronic and/or optoelectronic and/or acoustic and/or mechanical device, with the elements made in a surface layer of the initial support, and the process including the following stages:

a) Fixing a transfer support on the surface layer of the initial support;

b) Eliminating the part of the initial support that does not correspond to the surface layer;

c) Laterally defining the labels by cutting according to the thickness of the surface layer, with the cutting leaving zones to be broken off;

d) Grasping one or several labels to be transferred and tearing them off by means of energy intake in the corresponding zones that can be broken off;

e) Transfer and fixing the label or set of labels torn off in stage d) on the final support.

No figure.